

MTB02N03Q8-VB Datasheet N-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | |
|---------------------|----------------------------------------|--------------------|--|--|--|
| V _{DS} (V) | R_{DS(on)} (Ω) | I _D (A) | | | |
| 30 | 0.003 at V _{GS} = 10 V | 25 | | | |
| | 0.004 at V_{GS} = 4.5 V | 22 | | | |

FEATURES

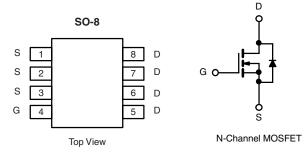
Halogen-free According to IEC 61249-2-21
Available



 Ultra Low On-Resistance Using High Density Trench Power MOSFET Technology

APPLICATIONS

- Synchronous Buck Low-Side
 - Notebook
 - Server
 - Workstation
- Synchronous Rectifier-POL



| Parameter | | Symbol | 10 s | Steady State | Unit |
|-----------------------------------------------------------------|------------------------|-----------------------------------|------|--------------|------|
| Drain-Source Voltage | | V _{DS} | 30 | | V |
| Gate-Source Voltage | | V _{GS} | ± 20 | | v |
| Continuous Drain Current (T _J = 150 °C) ^a | T _A = 25 °C | – I _D | 25 | 17 | |
| | T _A = 70 °C | | 20 | 13 | |
| Pulsed Drain Current (10 µs Pulse Width) | | I _{DM} | 70 | | А |
| Continuous Source Current (Diode Conduction) ^a | | ۱ _S | 2.9 | 1.3 | |
| Avalanche Current | | I _{AS} | 50 | | |
| | T _A = 25 °C | PD | 3.5 | 1.6 | W |
| Maximum Power Dissipation ^a | T _A = 70 °C | ' D | 2.2 | 1 | vv |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 | to 150 | °C |

| THERMAL RESISTANCE RATINGS | | | | | | |
|------------------------------------------|--------------|-------------------|---------|---------|------|--|
| Parameter | | Symbol | Typical | Maximum | Unit | |
| Maximum Junction-to-Ambient ^a | t ≤ 10 s | R _{thJA} | 29 | 35 | | |
| Maximum Junction-to-Ambient~ | Steady State | | 67 | 80 | °C/W | |
| Maximum Junction-to-Foot (Drain) | Steady State | R _{thJF} | 13 | 16 | | |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

| SPECIFICATIONS T _J = 25 °C, unless otherwise noted | | | | | | | |
|----------------------------------------------------------------------|---------------------|-------------------------------------------------------------------|----------|-------|-------|------|--|
| Parameter | Symbol | Test Conditions | Min. Typ | | Max. | Unit | |
| Static | | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \mu A$ 1.0 | | | 3.0 | V | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0$ V, $V_{GS} = \pm 20$ V | | | ± 100 | nA | |
| Zero Gate Voltage Drain Current | lana | $V_{DS} = 30 V, V_{GS} = 0 V$ | | | 1 | μΑ | |
| Zero Gale vollage Drain Current | IDSS | V_{DS} = 30 V, V_{GS} = 0 V, T_{J} = 55 °C | 55 °C | | 5 | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5 V$, $V_{GS} = 10 V$ | 30 | | | Α | |
| | P | V _{GS} = 10 V, I _D = 25 A | | 0.003 | | Ω | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 22 \text{ A}$ | | 0.004 | | | |
| Forward Transconductance ^a | 9 _{fs} | $V_{DS} = 15 \text{ V}, \text{ I}_{D} = 25 \text{ A}$ | | 110 | | S | |
| Diode Forward Voltage ^a | V _{SD} | $I_{\rm S}$ = 2.9 A, $V_{\rm GS}$ = 0 V | | 0.72 | 1.1 | V | |
| Dynamic ^b | | | | • | | | |
| Input Capacitance | C _{iss} | | | 6500 | | | |
| Output Capacitance | C _{oss} | V_{DS} = 15 V, V_{GS} = 4.5 V, I_D = 20 A | | 930 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | 610 | | | |
| Total Gate Charge | Qg | | | 45 | 70 | | |
| Gate-Source Charge | Q _{gs} | V_{DS} = 15 V, V_{GS} = 4.5 V, I_D = 20 A | | 20 | | nC | |
| Gate-Drain Charge | Q _{gd} | | | 16 | | | |
| Gate Resistance | Rg | f = 1.0 MHz | | 1.1 | | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 27 | 40 | | |
| Rise Time | t _r | V_{DD} = 15 V, R_L = 15 Ω | | 21 | 35 | | |
| Turn-Off Delay Time | t _{d(off)} | $\rm I_D \cong 1$ A, $\rm V_{GEN}$ = 10 V, $\rm R_g$ = 6 Ω | | 107 | 160 | ns | |
| Fall Time | t _f | | | 43 | 65 | | |
| Source-Drain Reverse Recovery Time | t _{rr} | $I_F = 2.9 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$ | | 45 | 70 | | |

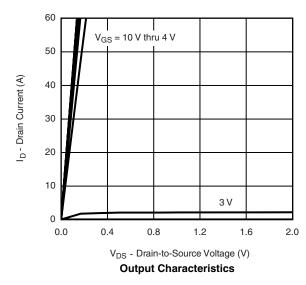
Notes:

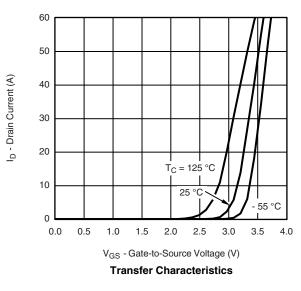
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

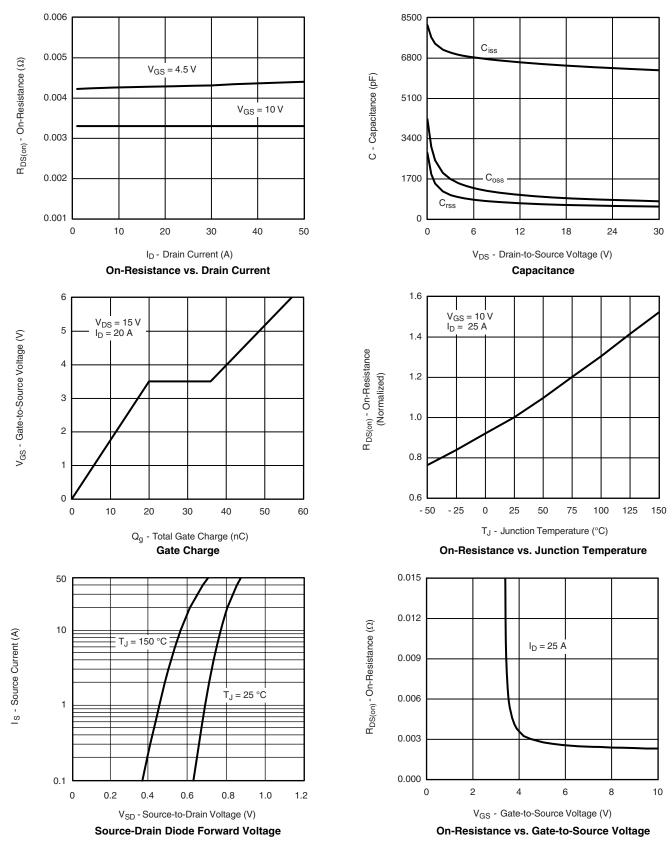




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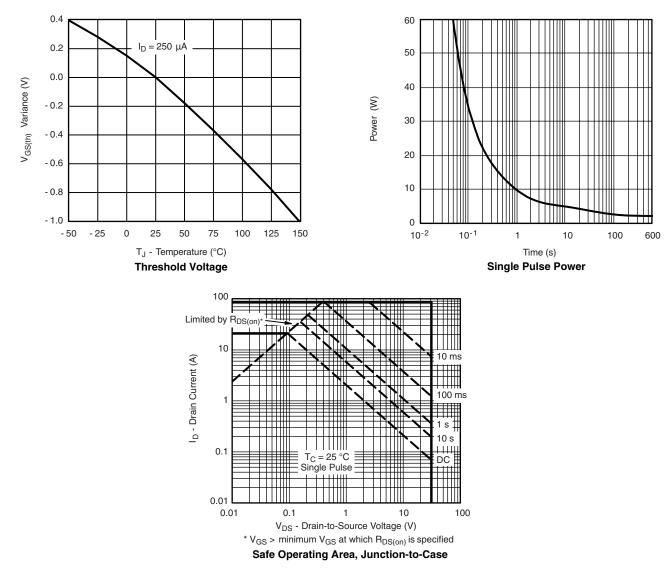




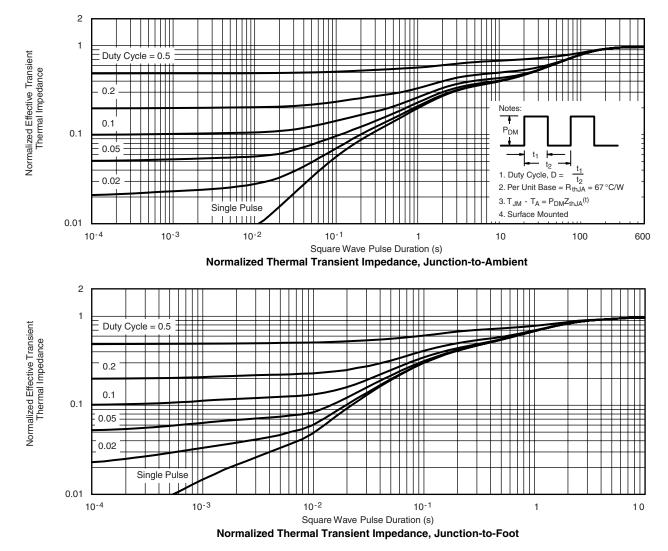




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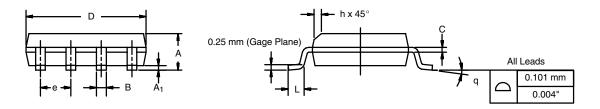


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





| | MILLIM | IETERS | INCHES | | | |
|---------------------------------------------|--------|--------|-----------|-------|--|--|
| DIM | Min | Мах | Min | Max | | |
| A | 1.35 | 1.75 | 0.053 | 0.069 | | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | | |
| E | 3.80 | 4.00 | 0.150 | 0.157 | | |
| е | 1.27 | BSC | 0.050 BSC | | | |
| н | 5.80 | 6.20 | 0.228 | 0.244 | | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | | |
| q | 0° | 8° | 0° | 8° | | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | | |
| ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498 | | | | | | |



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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